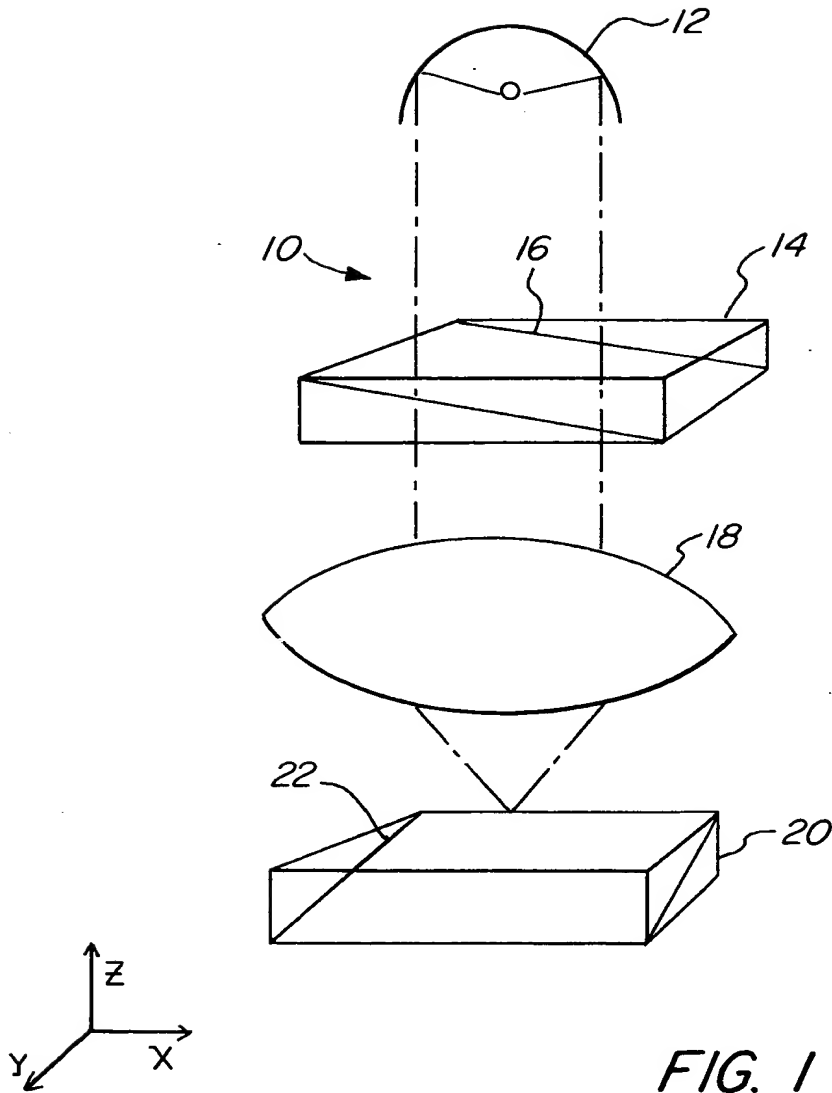
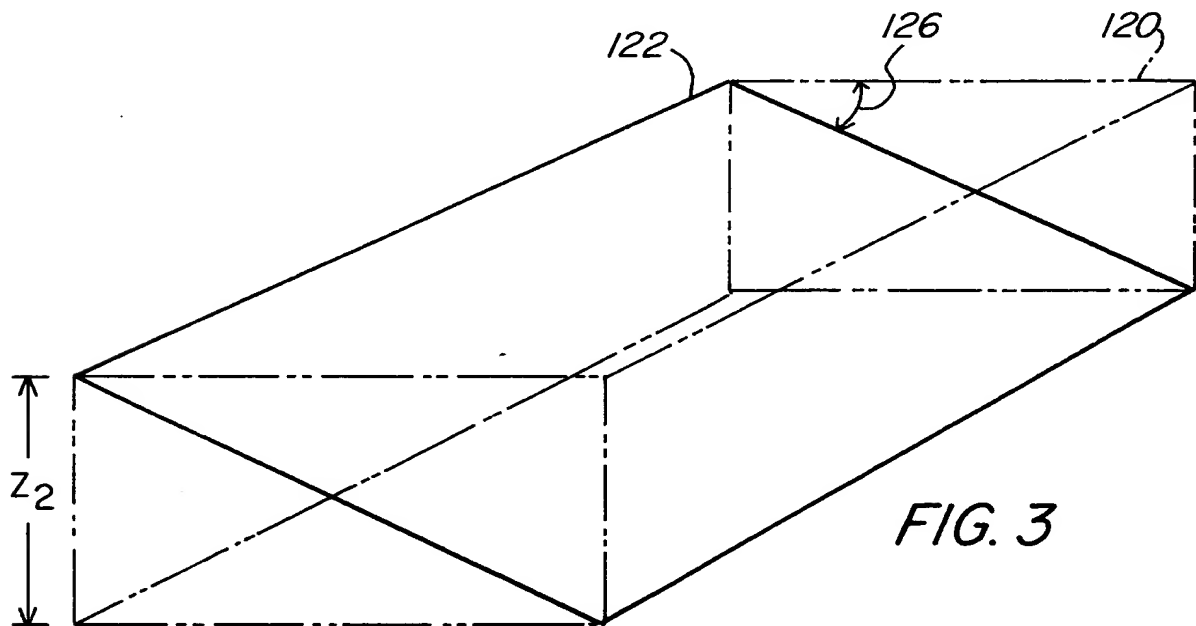
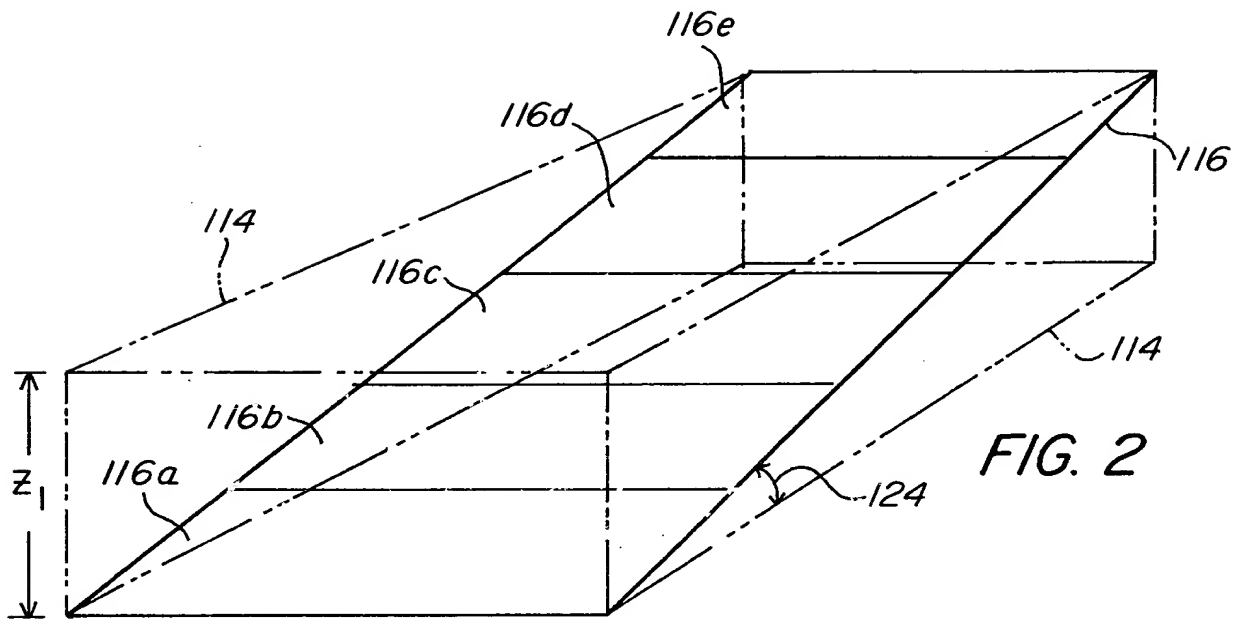
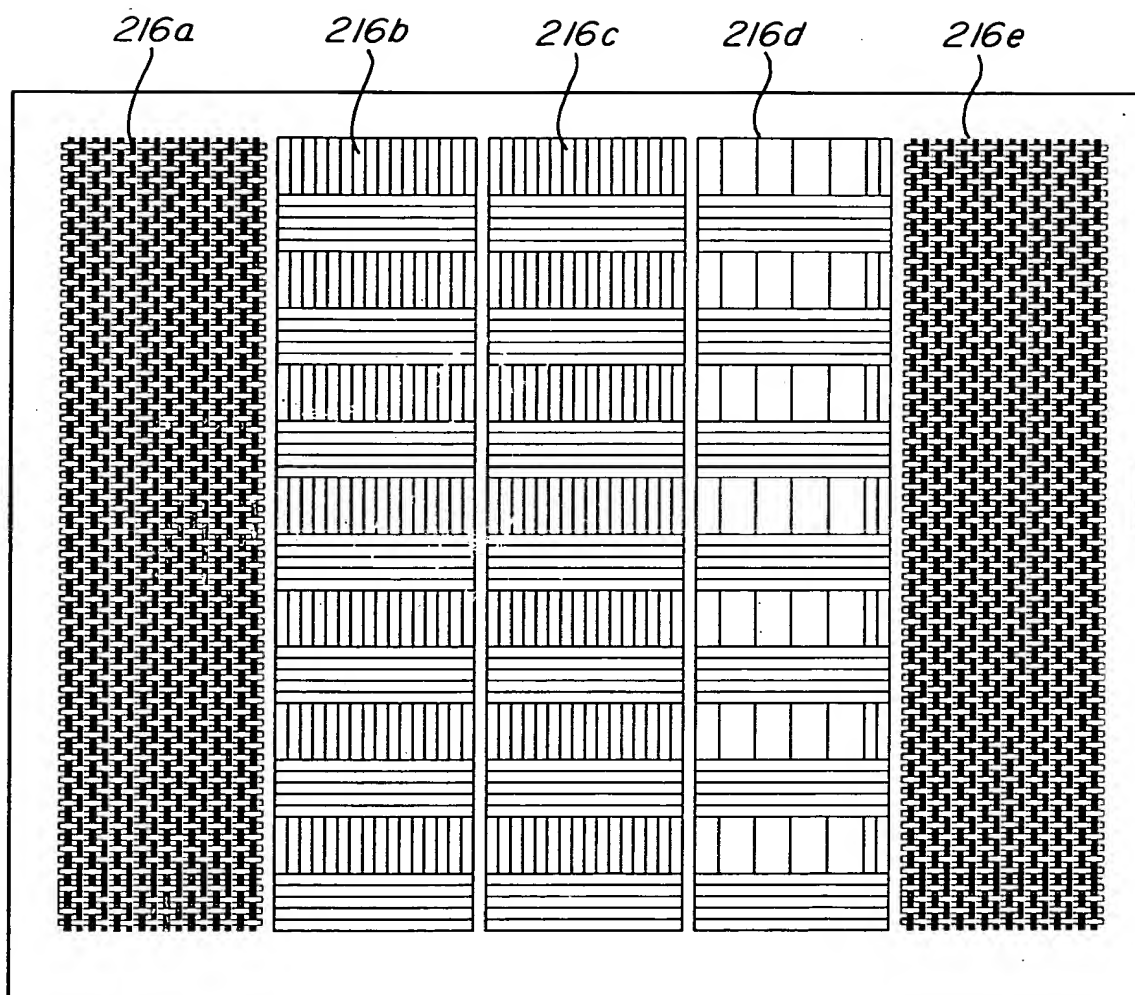


RECEIVED
FEB 05 2002
Technology Center 2600







216

FIG. 4

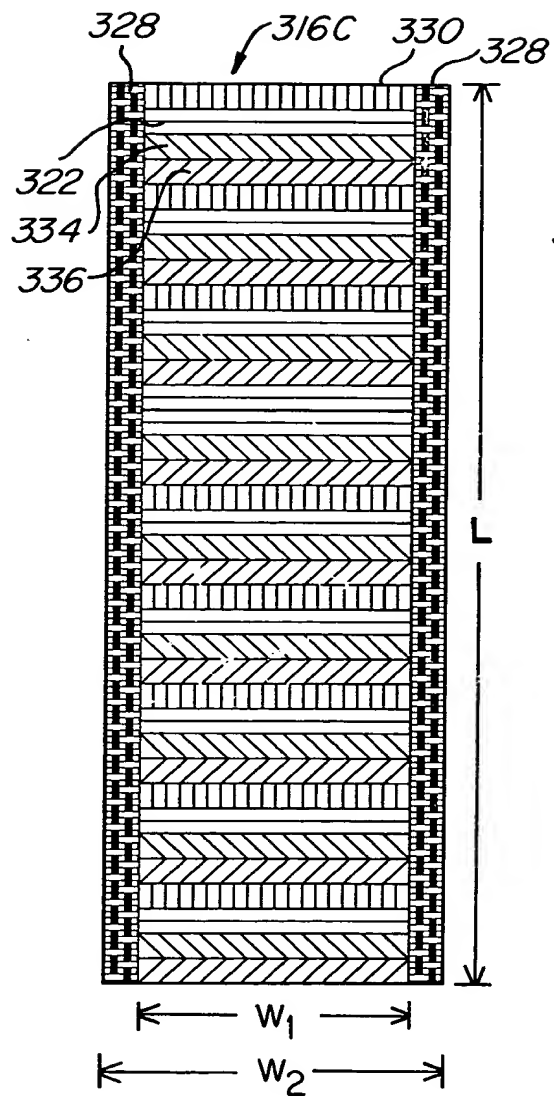


FIG. 5A

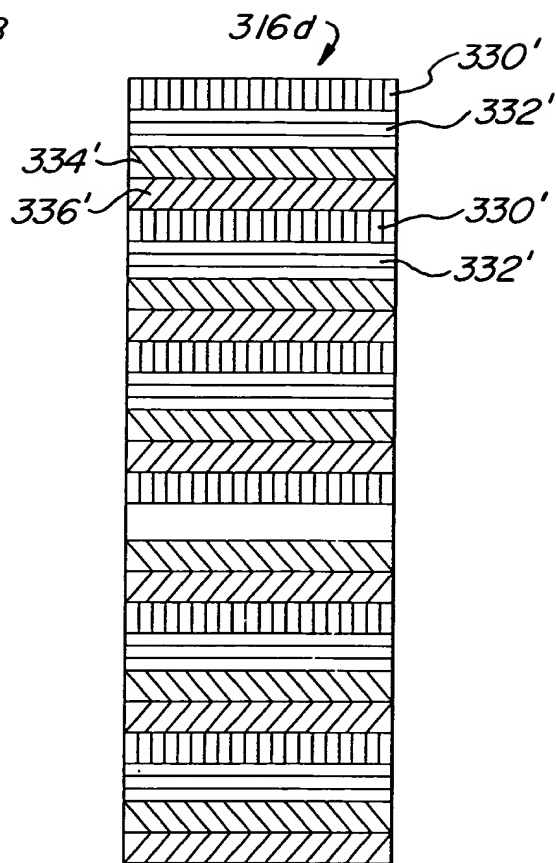


FIG. 5B

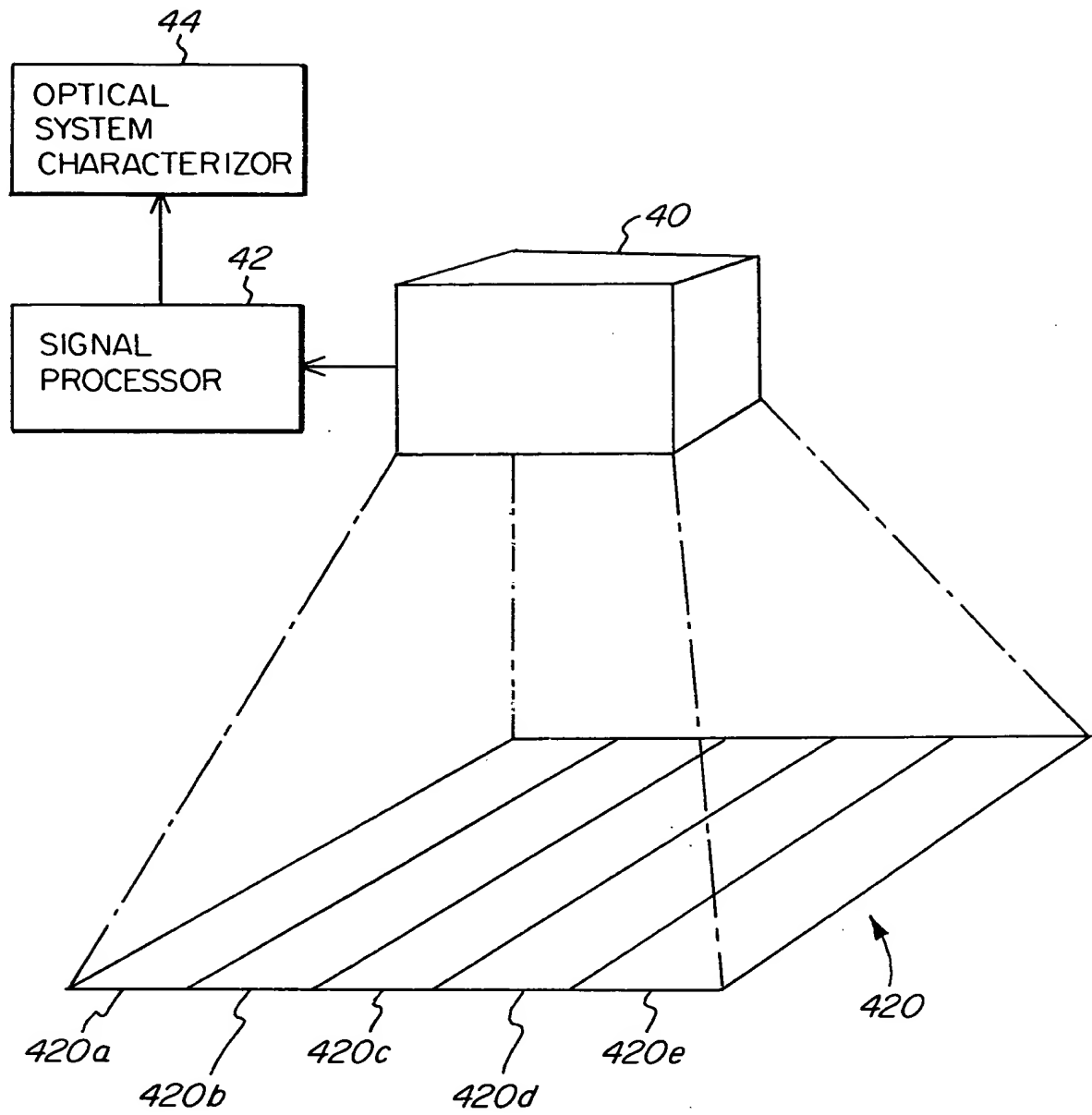


FIG. 6

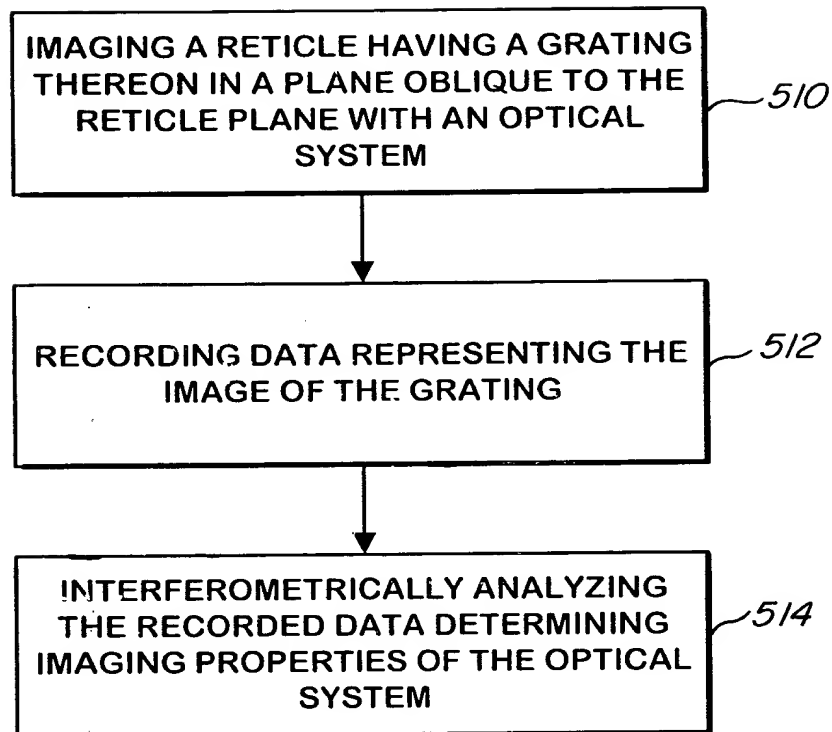


FIG. 7



FIG. 8A

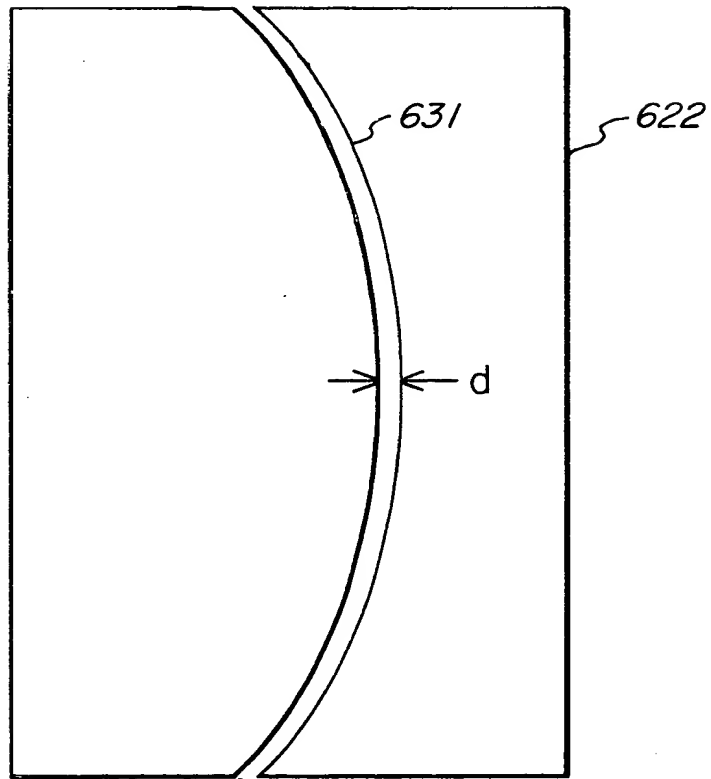
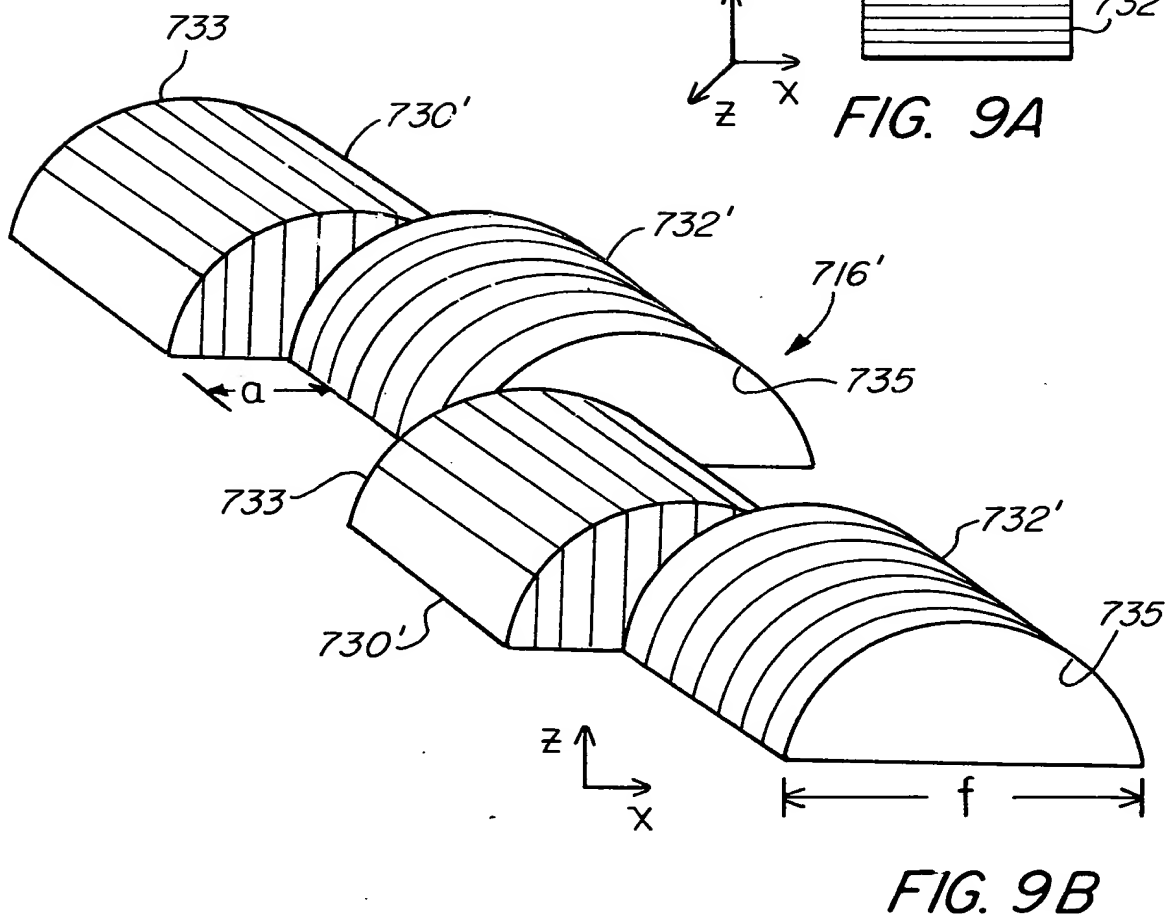
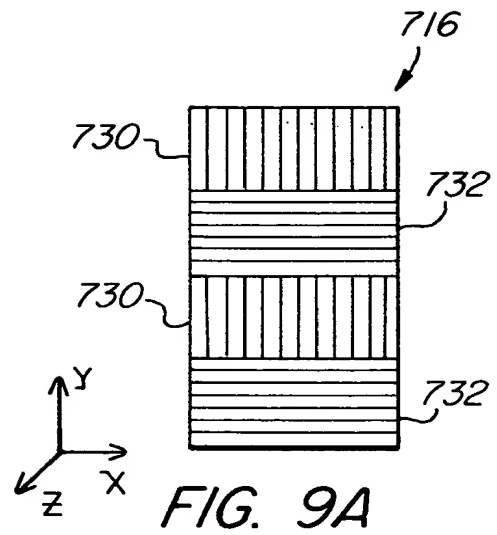


FIG. 8B



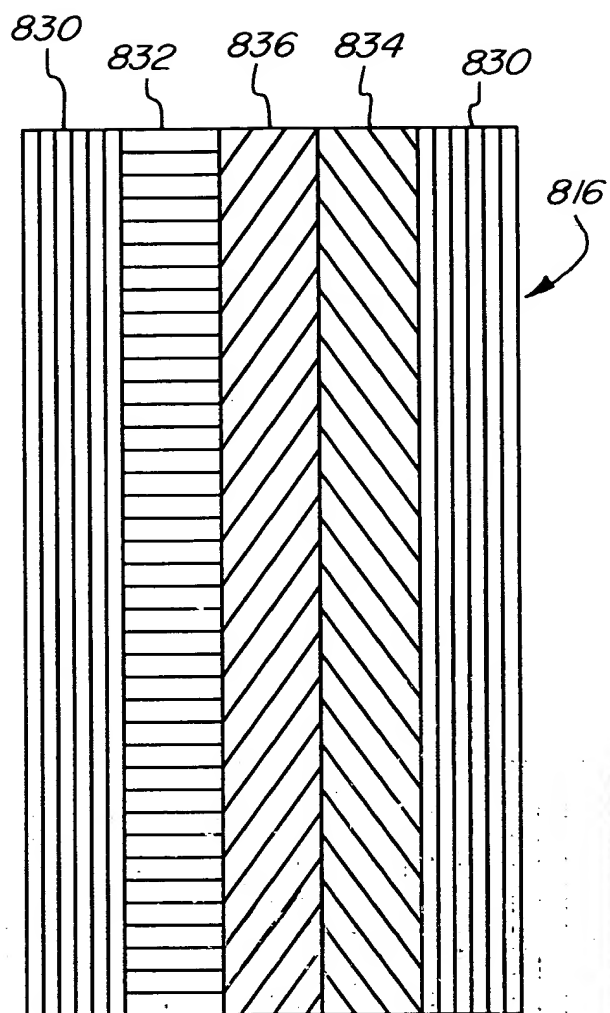


FIG. 10B

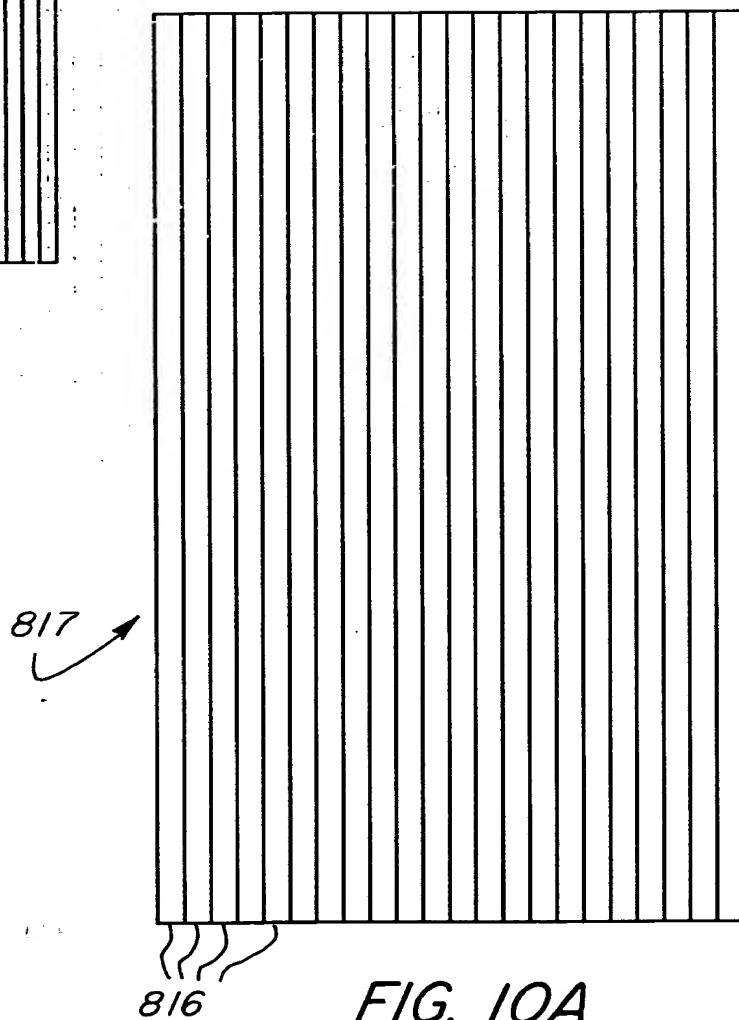


FIG. 10A

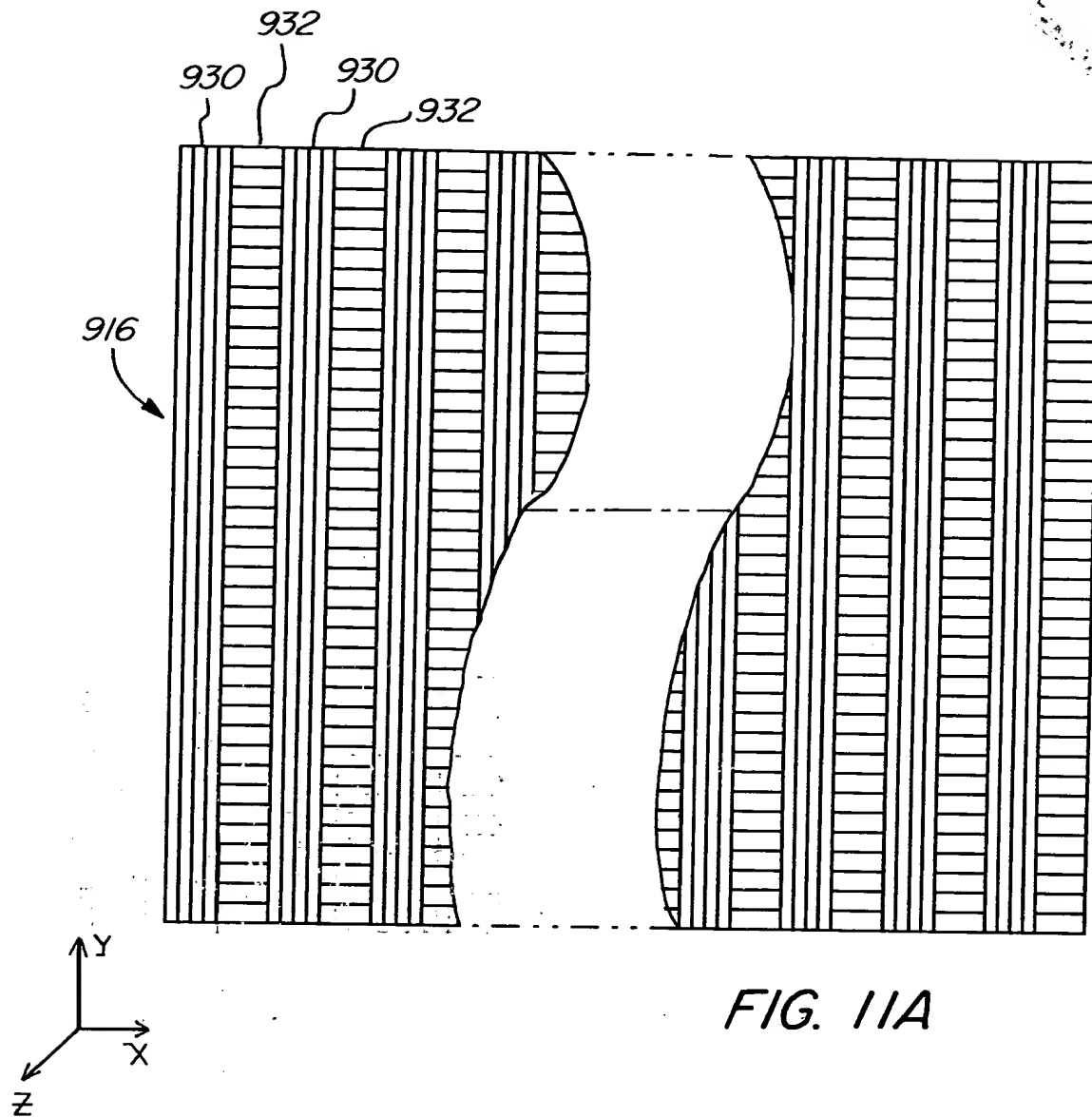


FIG. 11A

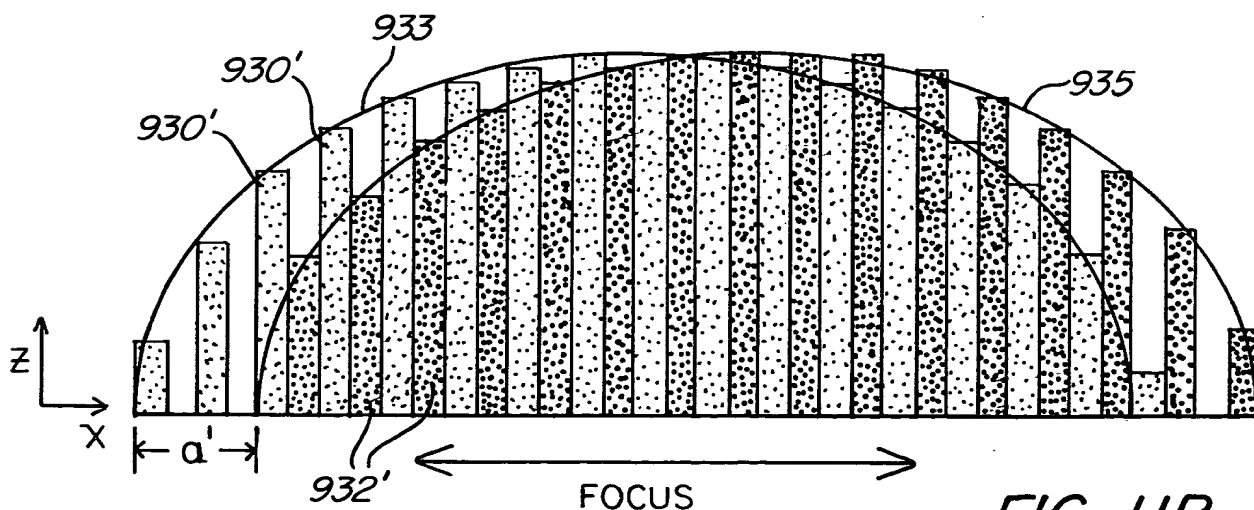


FIG. 11B

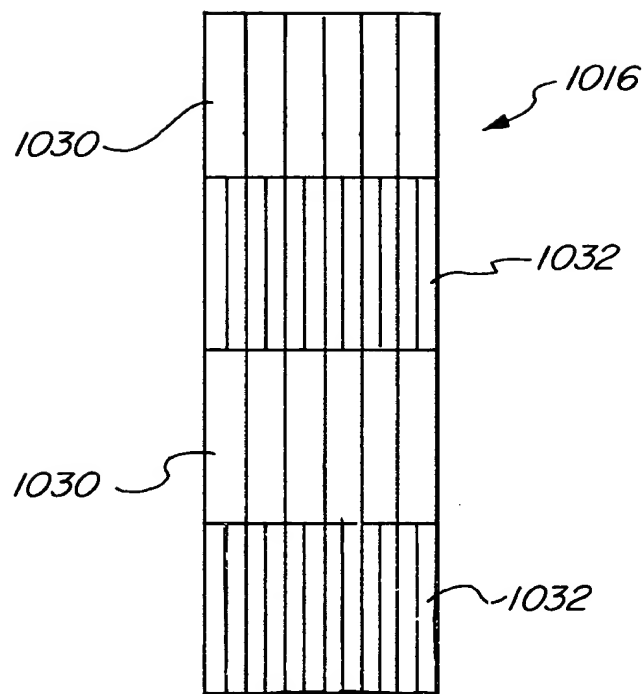


FIG. 12

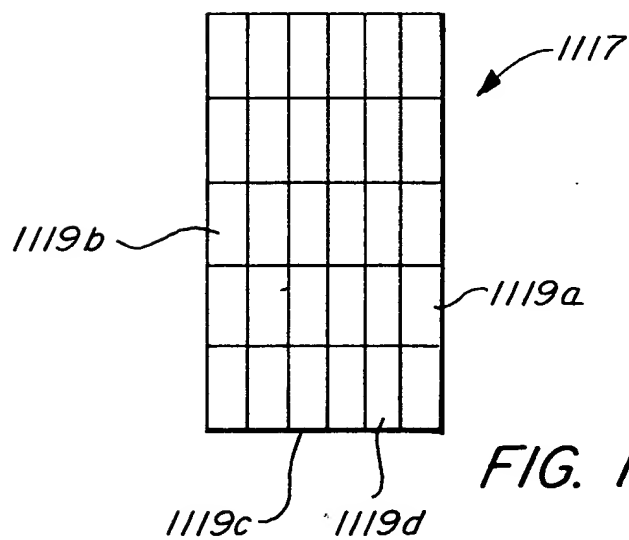


FIG. 13

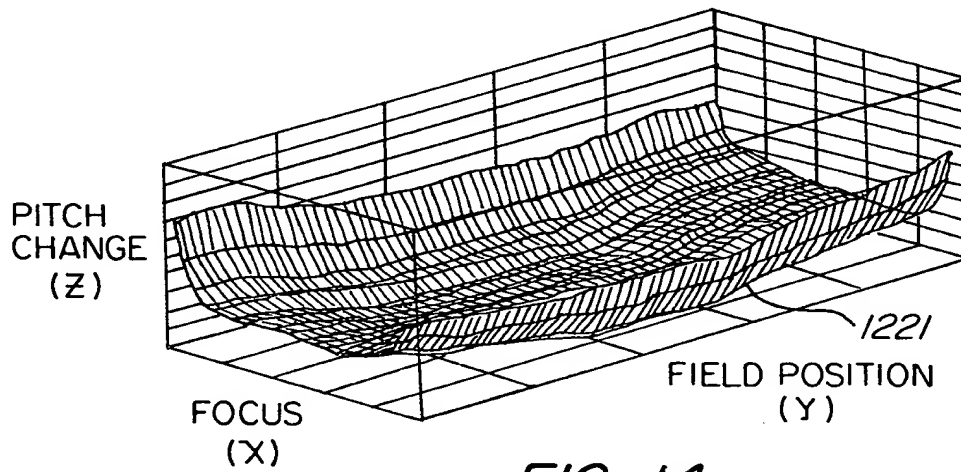


FIG. 14

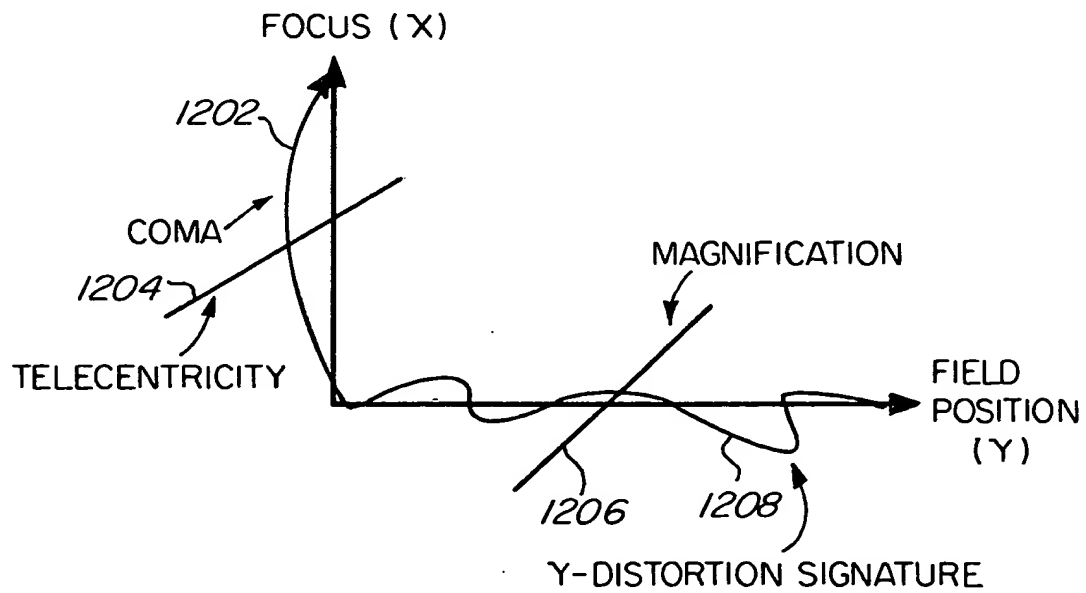


FIG. 15

FIG. 16A

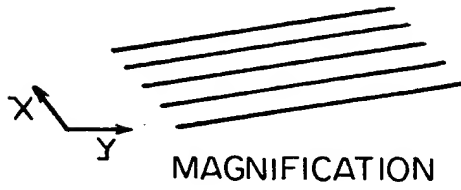


FIG. 16B

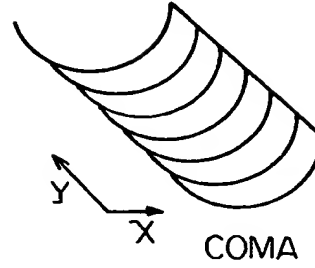


FIG. 16C

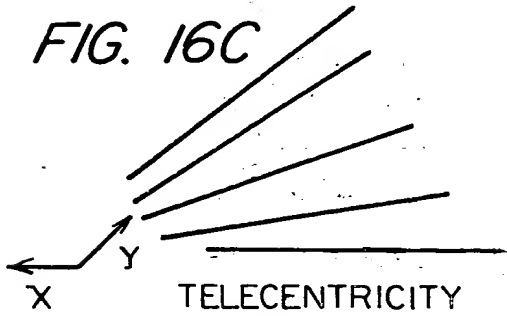


FIG. 16D

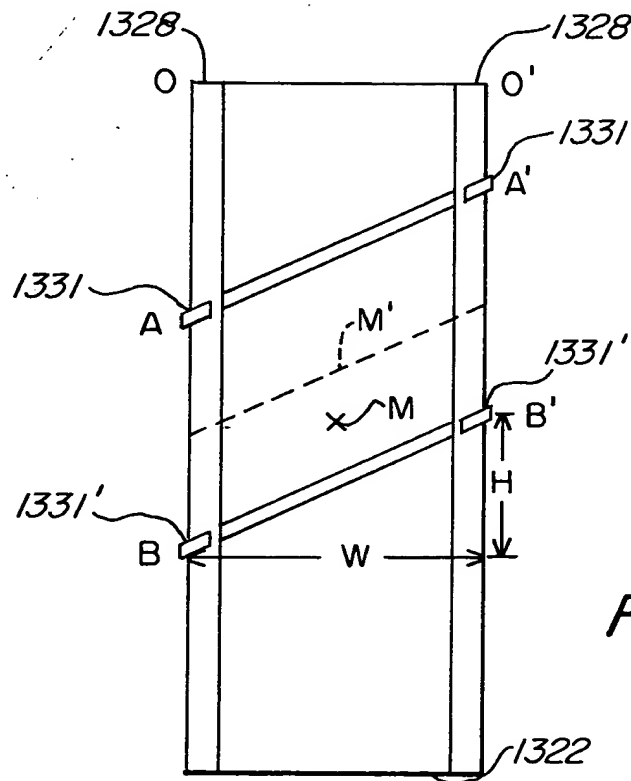
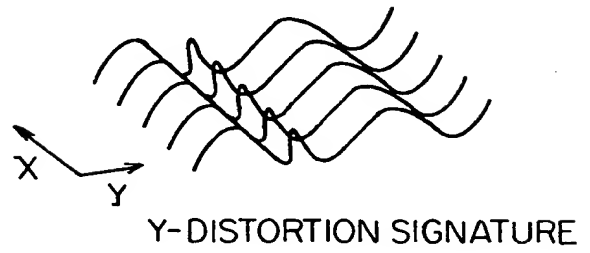


FIG. 17

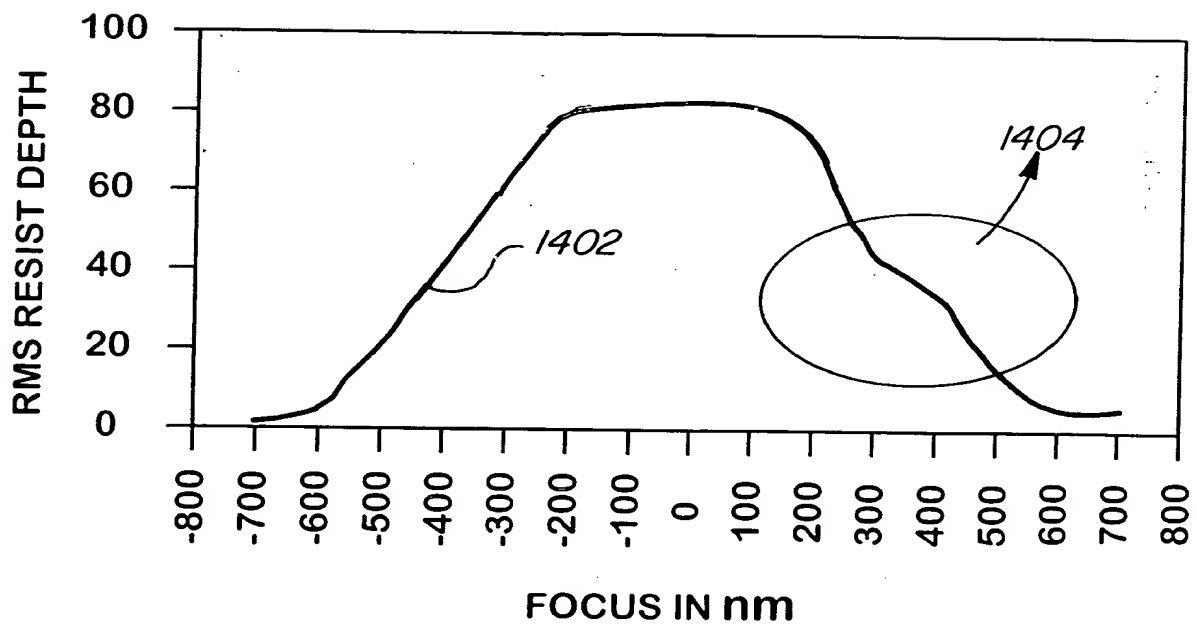


FIG. 18

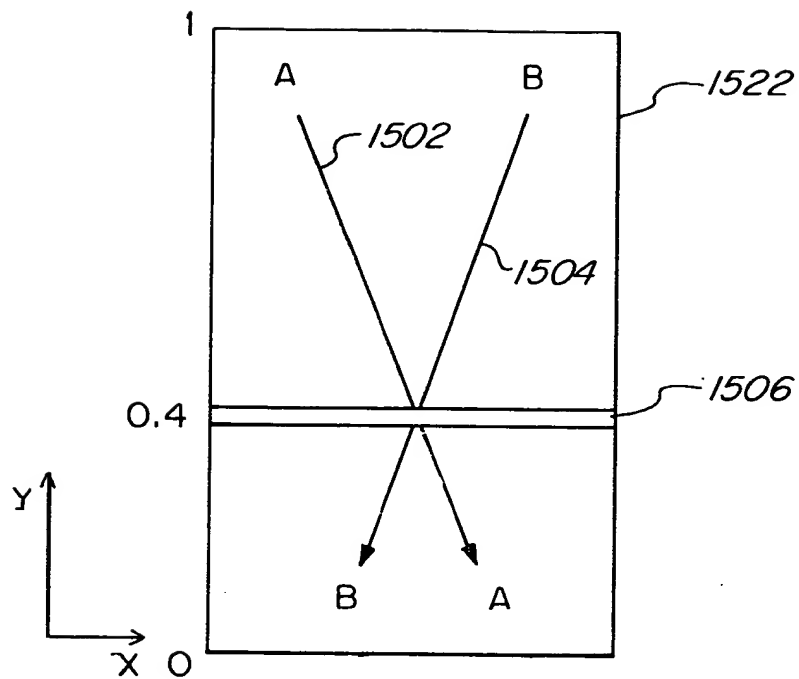


FIG. 19A

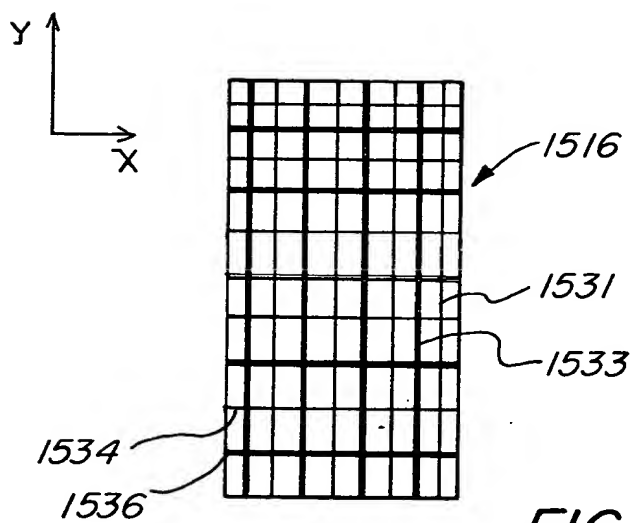


FIG. 19B